L Number	Hits	Search Text	DB	Time stamp
1	444	(361/729 or 361/730 or 174/50 or 174/51) and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 21:33
-	1	"20020020915"	USPAT; US-PGPUB	2004/05/25 14:16
-	5	59072757.pn. or 09199666.pn. or 04130453.pn. or 08148595.pn. or 07263619.pn.	JPO	2004/05/25 12:40
-	4528	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 14:17
-	368	257/787 and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 14:17
-	1412	(257/787 or 257/724 or 257/723) and capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 21:30
-	388	(257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 14:43
-	114	(257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 14:58
-	308	(257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 17:55
-	149	(257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 18:16
-	493	(257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 19:03
-	12542	(semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 19:04
-	11453	((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 19:04

-	3156	(((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 19:05
-	996	(((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 20:09
-	696	((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) not (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 19:31

–	2856	((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 19:31
–	1332	((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 19:32

—	5457	(((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and lead	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 20:09
—	4125	((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and lead) not (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) and lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 20:09

| | | 200 | (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and lead) not (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) and lead)) and 257/$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/25 20:12 |

| - | 172 | (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and lead) not (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) and lead)) and 438/$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/25 20:17 |

| - | | 511 | ((((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and lead) not (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) and lead)) and 361/$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/25 20:22 |

| | | 192 | (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and lead) not (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) and lead)) and 174/$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/25 20:24 |

| | | 162 | (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and lead) not (((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and 257/$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl$3 with capacitor) and lead)) and 29/$.ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/25 20:25 |